

1. Part Number: LBF7130-A0DXA

 2. Structure: The LED light bar  
 Mounted LED dice (bare chip) on substrate by array  
1series 30 string × 4series(Area) / 1Bar  
Aperture : 4 Area (LED: 120 chips)

3. Application: LCD Light Source

4. Maximum Conditions (1Bar) : (Ta= 25°C)

Item	Symbol	Maximum Condition	Unit
Operation Temperature	T <sub>op</sub>	-20~+80	°C
Storage Temperature	T <sub>st</sub>	-20~+80	°C
Forward Current (1 chip) *1	I <sub>F</sub>	100	mA
Surged Current (1chip) t <sub>p</sub> =100μs Duty ≤ 1/10	I <sub>FSM</sub>	0.3	A
Power Consumption	P <sub>tot</sub>	33	W
Junction Temperature	T <sub>JMAX</sub>	125	°C

\*1) Forward current would be changed by mounting condition (heat radiate condition) to a body.

5. LED Bar (1Bar) Characteristics : (Ta = 25°C)

Item	Symbol	Min.	Typ.	Max.	Unit	Condition
Forward Voltage	V <sub>F</sub>	11	12.4	13.8	V	I <sub>F</sub> = 2A
Luminous Flux	φ <sub>V</sub>	2475	2750	-	Lm	I <sub>F</sub> = 2A
Color Temperature	T <sub>cp</sub>	6020	6530	7040	K	I <sub>F</sub> = 2A

 \* Above Characteristics is initial value of immediate lighting LED .  
 And it is affected by the condition of LED Bar attached to heat spreader.

 \* Tolerance: V<sub>F</sub>:±0.2V, φ<sub>V</sub>:±7%, Color Temperature:±100K

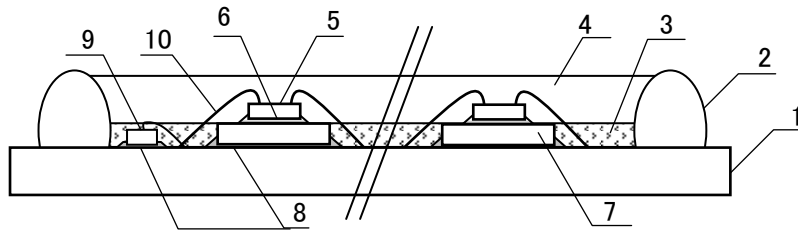
DESIGN	CHECK	APPROVAL	DATE: 2012/6/4	SPECIFICATION No. Target Spec
			REV. A	<b>ROHM Co.,Ltd.</b>

6. LED Module (4Bar / 1set) Characteristics (Ta=25°C)

Item	Symbol	MIN.	Typ.	MAX.	Unit	Condition
Input Current	I <sub>F</sub>	-	2	-	A	Par 1 terminal
Input Voltage	V <sub>f</sub>	44	49.6	55.2	V	I <sub>F</sub> = 2A
Total Luminous Flux	Φ <sub>v</sub>	9900	11000	-	Lm	I <sub>F</sub> = 2A
Color Temperature	T <sub>cp</sub>	6020	6530	7040	K	I <sub>F</sub> = 2A
Power Consumption (4Bar / 1set)	W	-	99	-	W	I <sub>F</sub> = 2A

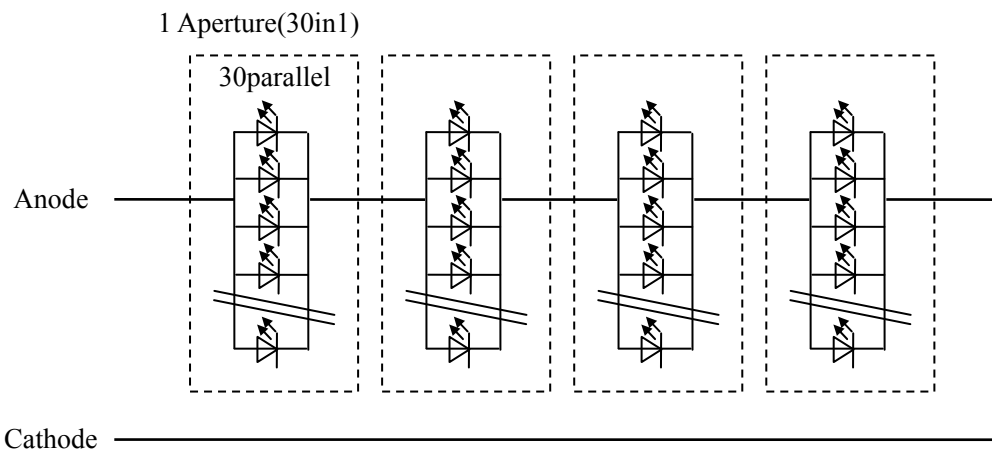
\* Above Characteristics is initial value of immediate lighting LED .  
And it is affected by the condition of LED Bar attached to heat spreader.  
\* Tolerance: V<sub>f</sub>:±0.8V, Φ<sub>v</sub>:±7%, Color Temperature:±100K

7. Structure

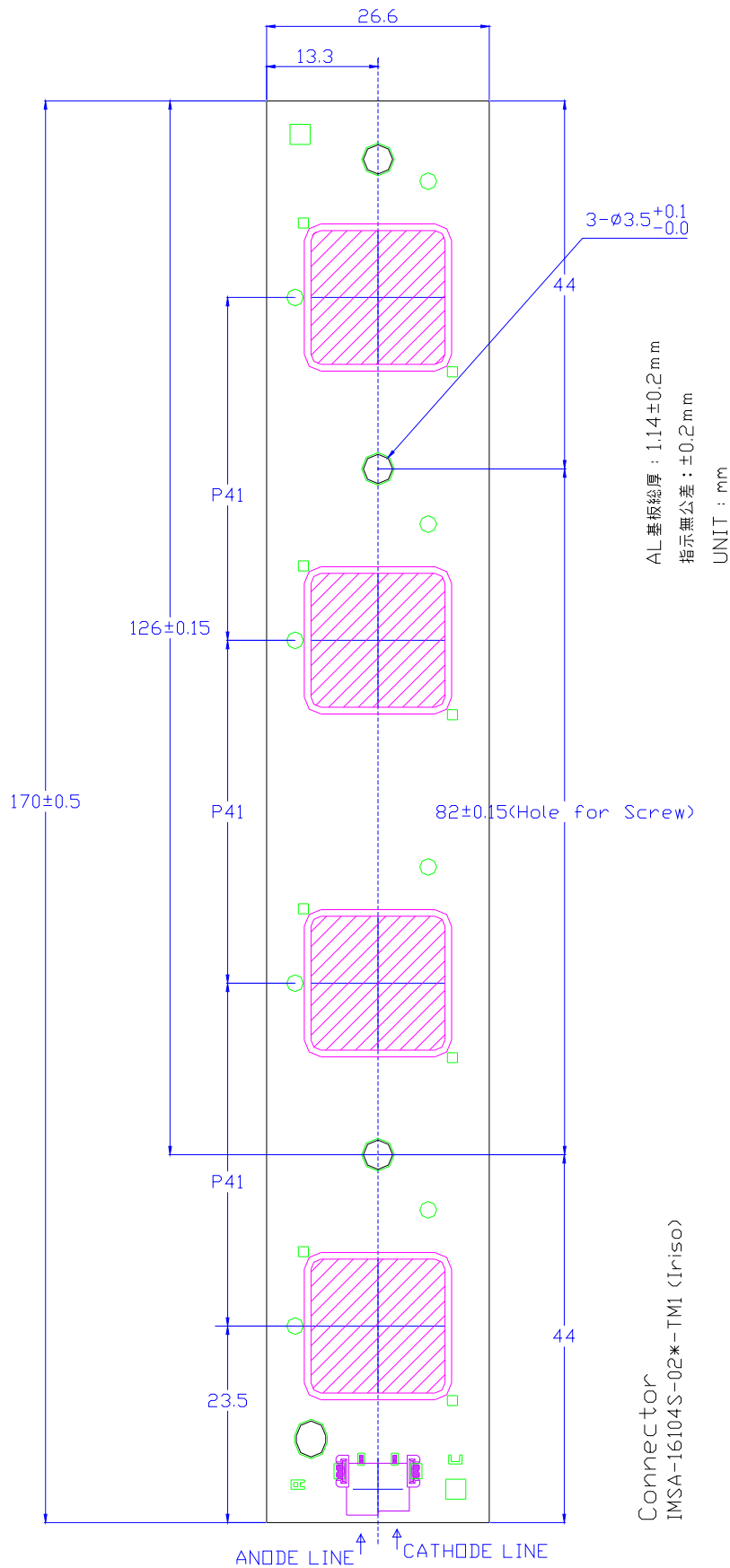


No	Parts Name	Material
1	Substrate	Al
2	Reflector	Silicone Resin
3	White Resin	Silicone Resin
4	Resin	Silicone Resin
5	LED Die	InGaN on AL <sub>2</sub> O <sub>3</sub>
6	Die Bond	Silicone Resin
7	Sub Mount Substrate	Si
8	Die Bond	Ag
9	Zener Diode	Si
10	Bonding Wire	Au

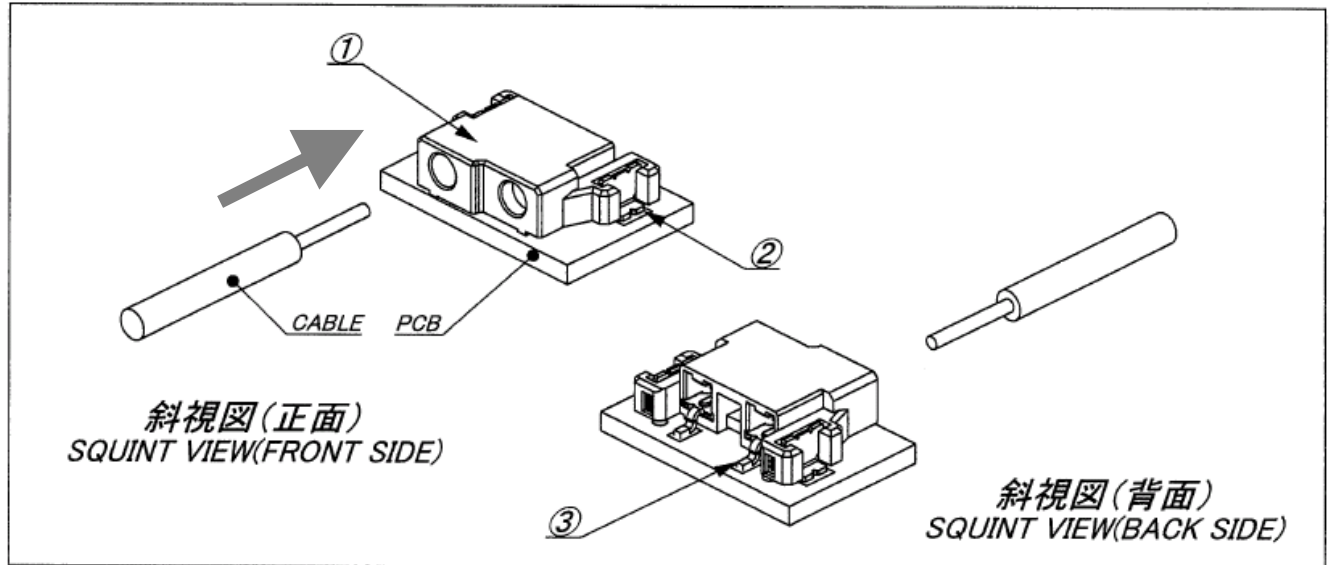
8. Circuit Diagram (1Bar)



9. Dimension

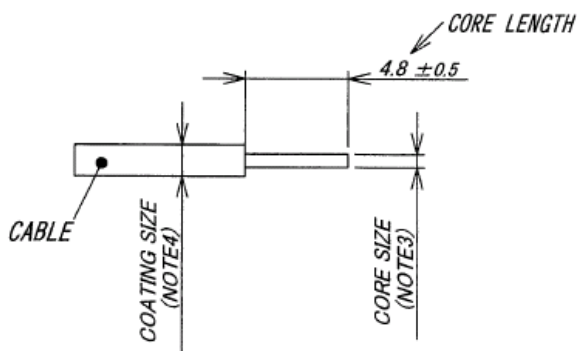


10.Connector



**NOTE**

1. 定格電圧・電流 ; 250V (AC/DC) 、 3A  
MAXIMUM RATING VOLTAGE ; 250V (AC/DC)  
MAXIMUM RATING CURRENT ; 3A
2. コプラナリティ ; 0.1max.  
COPLANARITY ; 0.1max.
3. ケーブル仕様 (芯線外形)  
CABLE CORE APPLICABLE (CORE SIZE)  
単線 ; AWG#22、芯線外形φ0.645±0.02  
SINGLE CORE ; AWG#22, CABLE CORE φ0.645±0.02  
撚線 ; AWG#24、芯線外形φ0.645±0.04  
TWISTED CORE ; AWG#24, CABLE CORE φ0.645±0.04  
(撚線の芯線外形は半田上げ処理後のものとする。)  
(AFTER SOLDER COATING)
4. ケーブル仕様 (被覆外形)  
CABLE COATING APPLICABLE (COATING SIZE)  
φ1.5max.
5. 当該品はウィスカの発生を通常品よりも抑制する効果を持たせた製品ではありますが、ウィスカの発生を無くす事を保証する製品ではありません。  
APPLICABLE PRODUCT HAS EFFECT TO SUPPRESS THE OCCURRENCE OF WHISKER THAN NORMAL. HOWEVER, IT IS NOT A PRODUCT THAT GUARANTEES THAT THERE IS NO OCCURRENCE OF WHISKER.



\* Above information is quoted form 「Iriso」.・・・IMS-A-16104S-02\*-TM1  
So above information is not covered by warranty.